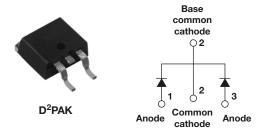


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HALOGEN

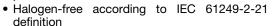
FREE

HEXFRED® Ultrafast Soft Recovery Diode, 2 x 15 A





- · Ultrafast recovery
- Ultrasoft recovery
- Very low I_{RRM}
- Very low Q_{rr}
- · Specified at operating conditions
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C



- Compliant to RoHS directive 2002/95/EC
- AEC-Q101 qualified

BENEFITS

- · Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- · Reduced snubbing
- · Reduced parts count

PRODUCT SUMMARY 600 V V_F at 15 A at 25 °C 1.7 V 2 x 15 A I_{F(AV)} t_{rr} (typical) 19 ns T_{.1} (maximum) 150 °C 80 nC Q_{rr} (typical) dI_{(rec)M}/dt (typical) at 125 °C 160 A/µs 4.0 A I_{RRM} (typical)

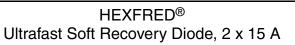
DESCRIPTION

VS-HFA30TA60CS is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 15 A per leg continuous current, the VS-HFA30TA60CS is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to "snap-off" during the tb portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA30TA60CS is ideally suited applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

| ABSOLUTE MAXIMUM RATINGS | | | | | | |
|--------------------------------------------------|-----------------------------------|-------------------------|---------------|-------|--|--|
| PARAMETER | SYMBOL | TEST CONDITIONS | VALUES | UNITS | | |
| Cathode to anode voltage | V_R | | 600 | V | | |
| Maximum continuous forward current per leg | I _F | T _C = 100 °C | 15 | | | |
| per device | | 1C = 100 C | 30 | А | | |
| Single pulse forward current | I _{FSM} | | 150 | ^ | | |
| Maximum repetitive forward current | I _{FRM} | | 60 | | | |
| Maximum pawar dissination | В | T _C = 25 °C | 74 | °C | | |
| Maximum power dissipation | P_{D} | T _C = 100 °C | 29 | C | | |
| Operating junction and storage temperature range | T _J , T _{Stg} | | - 55 to + 150 | W | | |

VS-HFA30TA60CSPbF

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| ELECTRICAL SPECIFICATIONS PER LEG (T _J = 25 °C unless otherwise specified) | | | | | | | |
|----------------------------------------------------------------------------------------------|-----------------|--------------------------------------------------------|------------|------|------|------|-------|
| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNITS |
| Cathode to anode breakdown voltage | V _{BR} | Ι _R = 100 μΑ | | 600 | - | - | |
| | V _{FM} | I _F = 15 A | | - | 1.3 | 1.7 | V |
| Maximum forward voltage | | I _F = 30 A | See fig. 1 | - | 1.5 | 2.0 | |
| | | I _F = 15 A, T _J = 125 °C | | - | 1.2 | 1.6 | |
| Maximum reverse | | V _R = V _R rated | See fig. 2 | - | 1.0 | 10 | |
| leakage current | I _{RM} | $T_J = 125$ °C, $V_R = 0.8 \times V_R$ rated | See lig. 2 | - | 400 | 1000 | μA |
| Junction capacitance | C _T | V _R = 200 V See fig. 3 | | - | 25 | 50 | pF |
| Series inductance | L _S | Measured lead to lead 5 mm from package body - 8.0 - n | | | nH | | |

| DYNAMIC RECOVERY CHARACTERISTICS PER LEG (T _J = 25 °C unless otherwise specified) | | | | | | | |
|-----------------------------------------------------------------------------------------------------|---------------------------|--------------------------------------|----------------------------------------------------------------------------------------|------|------|-------|---------------|
| PARAMETER | SYMBOL | TEST CO | MIN. | TYP. | MAX. | UNITS | |
| Reverse recovery time See fig. 5, 10 | t _{rr} | $I_F = 1.0 \text{ A}, dI_F/dt = 200$ | $A/\mu s$, $V_R = 30 V$ | - | 19 | - | ns |
| | t _{rr1} | T _J = 25 °C | $I_F = 15 \text{ A}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$ $V_R = 200 \text{ V}$ | - | 42 | 60 | |
| | t _{rr2} | T _J = 125 °C | | - | 70 | 90 | |
| Peak recovery current See fig. 6 | I _{RRM1} | T _J = 25 °C | | - | 4.0 | 6.0 | - A nC - A/μs |
| | I _{RRM2} | T _J = 125 °C | | - | 6.5 | 10 | |
| Reverse recovery charge See fig. 7 | Q _{rr1} | T _J = 25 °C | | - | 80 | 180 | |
| | Q _{rr2} | T _J = 125 °C | | - | 220 | 450 | |
| Peak rate of fall of recovery current during t _b See fig. 8 | dI _{(rec)M} /dt1 | T _J = 25 °C | | _ | 188 | - | |
| | dI _{(rec)M} /dt2 | T _J = 125 °C | | - | 160 | - | |

| THERMAL - MECHANICAL SPECIFICATIONS PER LEG | | | | | | | |
|---------------------------------------------|----------------------|------------------------------------|--------------|------|------------|------------------------|--|
| PARAMETER | SYMBOL | MBOL TEST CONDITIONS | | TYP. | MAX. | UNITS | |
| Lead temperature | T _{lead} | 0.063" from case (1.6 mm) for 10 s | - | - | 300 | °C | |
| Junction to case, single leg conducting | Б | | - | - | 1.7 | | |
| Junction to case, both legs conducting | —— R _{thJC} | | - | - | 0.85 | K/W | |
| Thermal resistance, junction to ambient | R _{thJA} | Typical socket mount | - | - | 80 | | |
| AA7.2.1.1 | | | - | 2.0 | - | g | |
| Weight | | | - | 0.07 | - | oz. | |
| Mounting torque | | | 6.0 (5.0) | - | 12 (10) | kgf · cm (lbf · in) | |
| Marking device | | Case style D ² PAK | HFA30TA60CS | | | | |





HEXFRED® Ultrafast Soft Recovery Diode, 2 x 15 A

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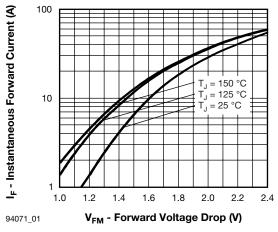


Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)

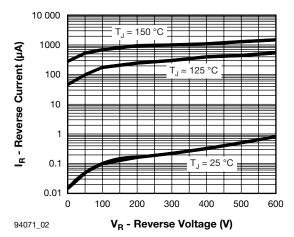


Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)

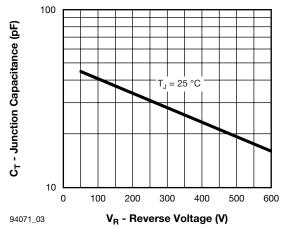


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)

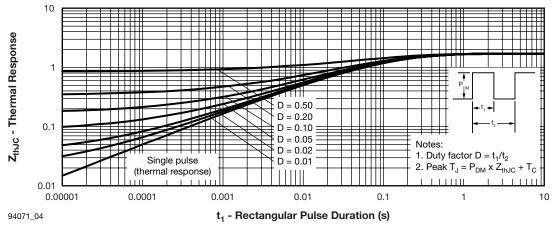


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)

VS-HFA30TA60CSPbF

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HEXFRED® Ultrafast Soft Recovery Diode, 2 x 15 A



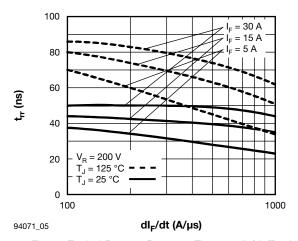


Fig. 5 - Typical Reverse Recovery Time vs. dl_F/dt (Per Leg)

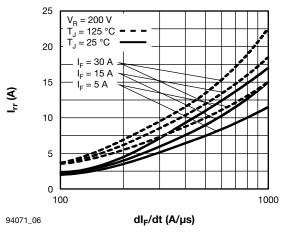


Fig. 6 - Typical Recovery Current vs. dl_F/dt (Per Leg)

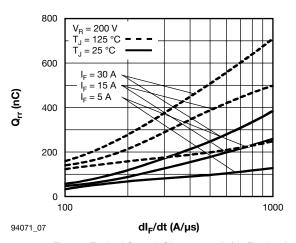


Fig. 7 - Typical Stored Charge vs. dI_F/dt (Per Leg)

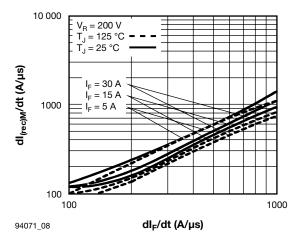


Fig. 8 - Typical $dI_{(rec)M}/dt$ vs. dI_F/dt (Per Leg)



HEXFRED® Ultrafast Soft Recovery Diode, 2 x 15 A

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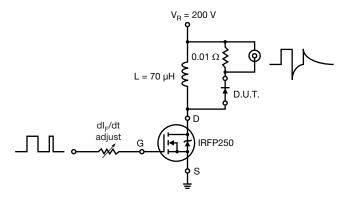
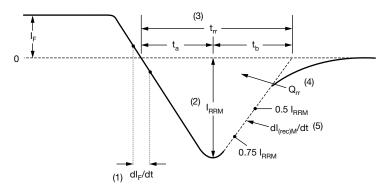


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) dl_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.
- (4) $\rm Q_{rr}$ area under curve defined by $\rm t_{rr}$ and $\rm I_{RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

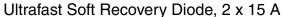
(5) dl_{(rec)M}/dt - peak rate of change of current during t_b portion of t_{rr}

Fig. 10 - Reverse Recovery Waveform and Definitions

VS-HFA30TA60CSPbF

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ORDERING INFORMATION TABLE

Device code

| VS- | HF | A | 30 | TA | 60 | С | S | TRL | PbF |
|-----|----|---|----|----|----|---|---|-----|-----|
| 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 |

1 - HPP product suffix

- HEXFRED® family

Process designator: A = Electron irradiated

4 - Current rating (30 = 30 A)

- Package outline (TA = TO-220, 3 leads)

6 - Voltage rating (60 = 600 V)

7 - Circuit configuration (C = Common cathode)

8 - S = D²PAK

9 - • None = Tube (50 pieces)

• TRL = Tape and reel (left oriented)

• TRR = Tape and reel (right oriented)

- PbF = Lead (Pb)-free

| LINKS TO RELATED DOCUMENTS | | | | | |
|----------------------------|--------------------------|--|--|--|--|
| Dimensions | www.vishay.com/doc?95046 | | | | |
| Part marking information | www.vishay.com/doc?95054 | | | | |
| Packaging information | www.vishay.com/doc?95032 | | | | |





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Revision: 11-Mar-11